SCOPE:

This specification applies to the Pb Free high current type SMD inductors for

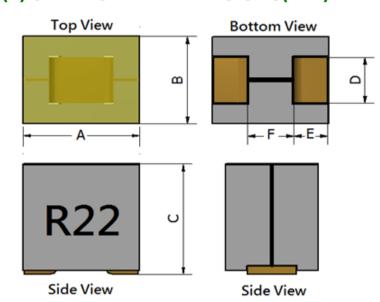
Warn: This product series can't be used in synchronous rectification circuit that is over 24V.

PRODUCT INDENTIFICATION

MSI - 110812V - R22 M -E-□□

- (T)
- (2)
- 3 4
 - (5)
- 1 Product Code
- 2 Dimensions Code
- **3 Inductance Code**
- **4** Tolerance Code
- **⑤ Inner Control Code**

(1) SHAPES AND DIMENSIONS(mm)



A: 10.7 Max. mm
B: 7.5 Max. mm
C: 12.0 Max. mm
D: 3.1 Typ. mm
E: 2.8 Typ. mm
F: 4.4 Typ. mm

Note: Standard of the printing area, parts of the surface are the qualified Marking non-directional printing limit

(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L: HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

Isat: WK3255BQ+ WK3265B (or equivalent)

(3) CHARACTERISTICS

(3)-1 Operate temperature range -40° C $\sim +125^{\circ}$ C (Including self temp. rise)

(3)-2 Storage temperature range $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$



TABLE 1

MAGLAYERS	Inductance	Percent	Resistance	Rated DC Current		Marking	
PT/NO.	L(µH)	Tolerance	RDC(mΩ)	Isat1(A)	Isat2(A)	Irms(A)	Marking
MSI-110812V-R15∐-E	0.15	K,L,M	0.15±5%	115	97	75	R15
MSI-110812V-R18∐-E	0.18	K,L,M	0.15±5%	85	72	75	R18
MSI-110812V-R22∐-E	0.22	K,L,M	0.15±5%	75	64	75	R22
MSI-110812V-R25∐-E	0.25	K,L,M	0.15±5%	66	56	75	R25
MSI-110812V-R27∐-E	0.27	K,L,M	0.15±5%	60	51	75	R27
MSI-110812V-R30∐-E	0.30	K,L,M	0.15±5%	55	45	75	R30
MSI-110812V-R32∐-E	0.32	K,L,M	0.15±5%	51	43	75	R32

※ Test Frequency: 100kHz/1.0V

※ ☐ specify the inductance tolerance,K(±10%),L(±15%),M(±20%)

※ Isat1: Based on inductance change (△L/Lo: drop 20% Typ.)@ ambient temp. 25°C

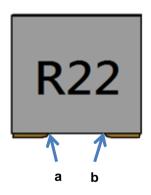
※ Isat2: Based on inductance change (△L/Lo: drop 20% Typ.)@ ambient temp.100℃

Irms: Based on temperature rise (△T: 40°C TYP.)

Rated DC Current: The less value which is Isat1 or Irms.

RDC TEST POINT

The nominal DCR is measured from point





(4) RELIABILITY TEST METHOD

ELECTRICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Temperature	∆L/L20°C ≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85 $^{\circ}\mathrm{C}$,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be △L/L20°C ≦±10%.

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS			
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		in figure 1 and a load applied unitil the figure in the arrow			
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)			
	no mechanical	PCB dimension shall the page 7/9			
	damage or elec-	F(Pressurization)			
	trical damege.	\Box			
		R5 45±2 45±2			
		10 20 R340			
		PRESSURE ROD figure-1			



MECHANICAL

TEST ITEM		SPECIFICATION					
Vibration	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board					
		and when a vibration having an amplitude of 1.52mm					
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should					
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.					
	damage.	(A total of 6 hours)					
Solderability	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated					
	More than 90%	over the whole of the sample before hard, the sample shall					
		then be preheated for about 2 minutes in a temperature of					
		130~150℃ and after it has been immersed to a depth 0.5mm					
		below for 3±0.2 seconds fully in molten solder M705 with					
		a temperature of 245±5℃.					
		More than 90% of the electrode sections shall be couered					
		with new solder smoothly when the sample is taken out of					
		the solder bath.					
Resistance to	There shall be	Temperature profile of reflow soldering					
Soldering heat	no damage or	Soldering soldering					
(reflow soldering)	problems.	(Peak temperature 260±3°C 10 sec)					
		(Peak temperature 260±3°C 10 sec) Pre-heating 150 Pre-heating Soldering (Peak temperature 260±3°C 10 sec) Slow cooling (Stored at room					
		30 sec Min (230+0 °C)					
		p 150 Pre-heating					
		Slow cooling (Street of the street)					
		(Stored at room temperature)					
		2 min sec. 2 min. or more					
		The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time.					
		The specimen shall be stored at standard atmospheric conditi for 1 hour, after which the measurement shall be made.					



ENVIROMENT CHARACTERISTICS

TEST ITEM		SPECIFICATION						
High temperature	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in an atmospere with						
storage		a temperature of 125℃ and a normal humidity.						
	There shall be	Upon co	Upon completion of the measurement shall be made after the					
	no mechanical	sample has been left in a normal temperature and normal						
	damage.	humidity for 1 hour.						
Low temperature	∆L/Lo≦±5%	The san	The sample shall be left for 96±4 hours in an atmosphere with					
storage		a tempe	a temperature of -40±3℃.					
	There shall be	Upon co	Upon completion of the test, the measurement shall be made					
	no mechanical	after the	samp	ole has been left in a no	ormal temperature and	d		
	damage.	normal humidity for 1 hour.						
Change of	∆L/Lo≦±5%	The san	The sample shall be subject to 5 continuos cycles, such as shown					
temperature		in the ta	ble 2 l	below and then it shall	be subjected to stand	dard		
	There shall be	atmosp	atmospheric conditions for 1 hour, after which measurement					
	no other dama-	shall be	made					
	ge of problems							
				table 2				
				Temperature	Duration			
			1	-40±3℃	30 min.			
			-	(Themostat No.1)				
			Standard 2	Standard	No.1→No.2			
				atmospheric				
			3	125±2 ℃	30 min.			
				(Themostat No.2)				
			4	Standard	No.2→No.1			
				atmospheric				
Moisture storage	∆L/Lo≦±5%	The san	nple sl	nall be left for 96±4 hou	ırs in a temperature o	f		
_		40±2°C and a humidity(RH) of 90∼95%.						
	There shall be	Upon completion of the test, the measurement shall be made after the sample has been left in a normal temperature and normal humidity more than 1 hour.						
	no mechanical							
	damage.							
Test conditions :	•							
The sa	ample shall be reflow	v soldere	d onto	the printed circuit boa	rd in every test.			

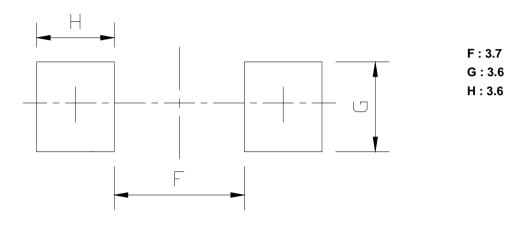


(5) LAND DIMENSION (Ref.)

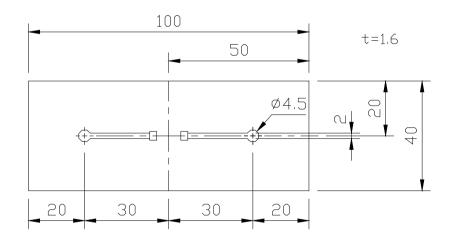
PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS(mm)

(STANDARD PATTERN)



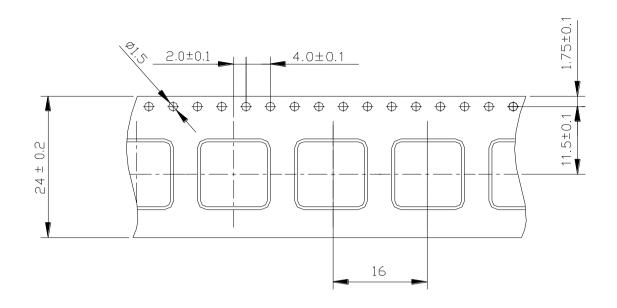
(5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD



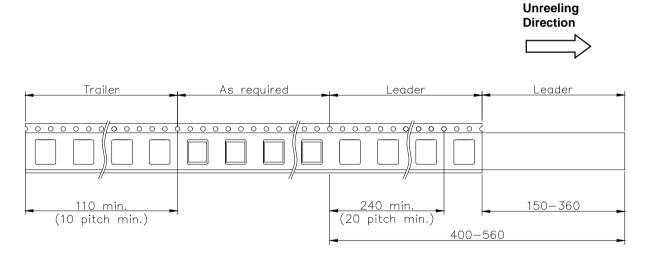


(6) PACKAGING

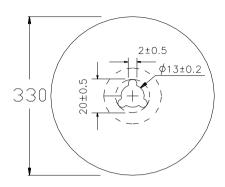
(6)-1 CARRIER TAPE DIMENSIONS (mm)

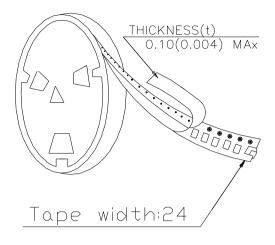


(6)-2 TAPING DIMENSIONS (mm)



(6)-3 REEL DIMENSIONS (mm)





(6)-4 QUANTITY

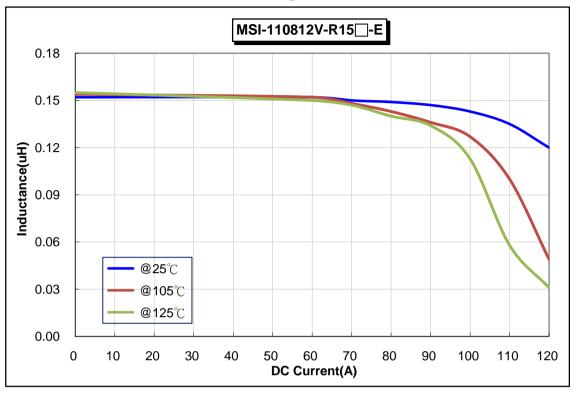
300 pcs/Reel

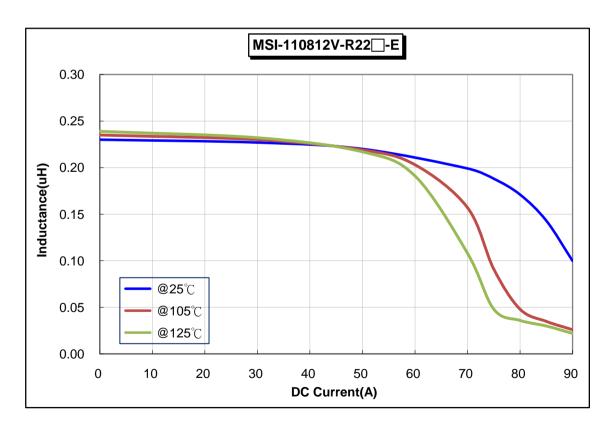
The products are packaged so that no damage will be sustained.

Please note that the contents may change without any prior notice due to reasons such as upgrading.



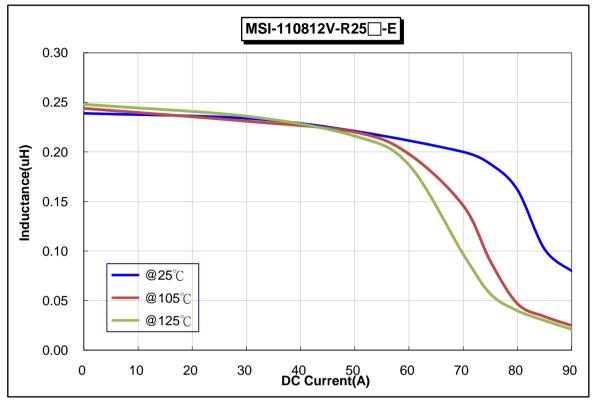
INDUCTANCE vs. DC CURRENT@100kHz/1.0V

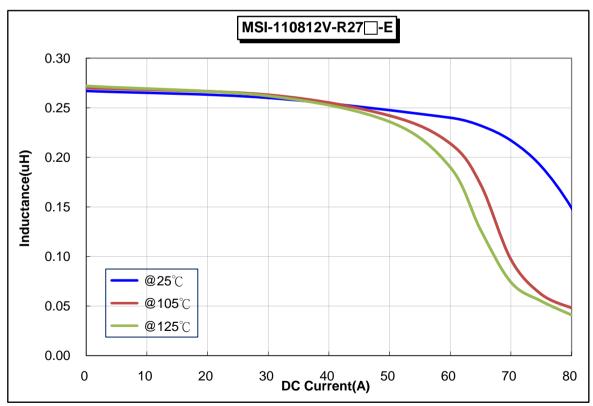






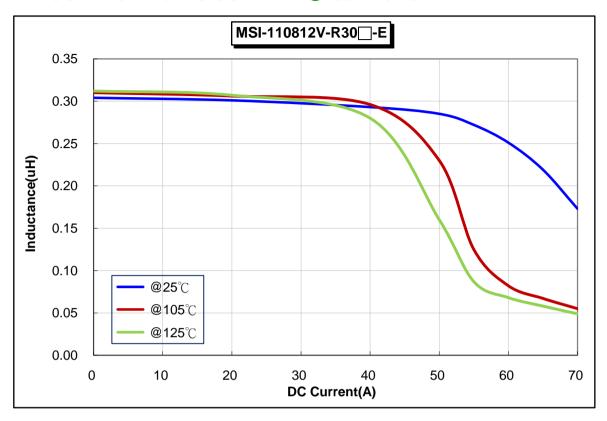
INDUCTANCE vs. DC CURRENT@100kHz/1.0V







INDUCTANCE vs. DC CURRENT@100kHz/1.0V





Temperature Rise vs. DC Current

